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Substitute for form 1449/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)			Complete if Known		
			Application Number	10/594,671	
			Filing Date	September 28, 2006	
			First Named Inventor	Masahiro TOJO	
			Art Unit	1644 1626	
			Examiner Name	Not Yet Assigned	
Sheet	1	of	1	Attorney Docket Number	0216-0524PUS1

Reitsang Shiao

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
	AA*	US-3,642,858-A	02-15-1972	Frevel et al.	
	AB*	US-4,181,676-A	01-01-1980	Buysch et al.	
	AC*	US-4,062,884-A	12-13-1977	Romano et al.	
	AD*	US-4,307,032-A	12-22-1981	Krimm et al.	
	AE*	US-4,681,967-A	07-21-1987	Green	
	AF*	US-4,661,609-A	04-28-1987	Knifton	
	AG*	US-4,691,041-A	09-01-1987	Duranleau et al.	
	AH*	US-4,734,518-A	03-29-1988	Knifton	
	AI*	US-3,803,201-A	04-09-1974	Gilpin et al.	
	AJ*	US-5,847,189-A	12-8-1998	Tojo et al.	
	AK*	US-6,479,689-A	11-12-2002	Tojo et al.	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)	MM-DD-YYYY			
	BA	JP-54-63023-A	05-21-1979			
	BB	JP-54-148726-A	11-21-1979			
	BC	JP-55-64550-A	05-15-1980			
	BD	JP-55-64551-A	05-15-1980			
	BE	JP-56-10144-A	02-02-1981			
	BF	JP-63-238043-A	10-04-1988			
	BG	JP-4-198141-A	07-17-1992			
	BH	JP-4-230243-A	08-19-1992			
	BI	JP-5-213830-A	08-24-1993			
	BJ	JP-6-9507-A	01-18-1994			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. * CITE NO.: Those application(s) which are marked with an single asterisk (*) next to the Cite No. are not supplied (under 37 CFR 1.98(a)(2)(iii)) because that application was filed after June 30, 2003 or is available in the IFW. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	/Rei Tsang Shiao/ (02/17/2009)	Date Considered	
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Birch, Stewart, Kolasch & Birch, LLP

GMM/srm

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /RS/

MEMORANDUM ON INFORMATION DISCLOSURE STATEMENT

- (1) U.S. Patent No. 3,642,858
- (2) U.S. Patent No. 4,181,676
- (3) U.S. Patent No. 4,062,884
- (4) U.S. Patent No. 4,307,032
- (5) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 54-63023
- (6) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 54-148726
- (7) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 55-64550
- (8) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 55-64551
- (9) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 56-10144
- (10) U.S. Patent No. 4,681,967
- (11) U.S. Patent No. 4,661,609
- (12) Unexamined Japanese Patent Application Laid-Open Specification No. Sho 63-238043
- (13) U.S. Patent No. 4,691,041
- (14) U.S. Patent No. 4,734,518
- (15) U.S. Patent No. 3,803,201
- (16) Unexamined Japanese Patent Application Laid-Open Specification No. Hei 4-198141
- (17) Unexamined Japanese Patent Application Laid-Open Specification No. Hei 4-230243

/Rei Tsang Shiao/ (02/17/2009)

- 1 -

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /RS/

- (18) Unexamined Japanese Patent Application Laid-Open Specification No. Hei 5-213830
- (19) Unexamined Japanese Patent Application Laid-Open Specification No. Hei 6-9507
- (20) U.S. Patent No. 5,847,189
- (21) U.S. Patent No. 6,479,689
- (22) Unexamined Japanese Patent Application Laid-Open Specification No. 2002-308804
- (23) Unexamined Japanese Patent Application Laid-Open Specification No. 2004-131394
- (24) Unexamined Japanese Patent Application Laid-Open Specification No. 2002-371037

References (1) to (23) are documents which are cited as Patent Documents 1 to 23 in the present specification. The references represented by each Patent Document Number are listed in paragraph [0014] of the present specification. Specifically:

Reference (1) is described in paragraphs [0002] and [0004] of the present specification;

Reference (2) is described in paragraphs [0002] and [0004] of the present specification;

Reference (3) is described in paragraphs [0002] and [0005] of the present specification;

Reference (4) is described in paragraphs [0002] and [0005] of the present specification;

Reference (5) is described in paragraphs [0002] and [0004] of the present specification;

Reference (6) is described in paragraph [0002] of the present specification;

Reference (7) is described in paragraph [0002] of the present specification;

Reference (8) is described in paragraph [0002] of the present specification;

Reference (9) is described in paragraphs [0002] and [0004] of the present specification;

Reference (10) corresponds to Unexamined Japanese Patent Application Laid-Open Specification No. Sho 59-106436, which is described in paragraph [0002] of the present specification;

Reference (11) is described in paragraphs [0002] and [0006] of the present specification;

Reference (12) is described in paragraphs [0002] and [0006] of the present specification;

Reference (13) is described in paragraphs [0002] and [0006] of the present specification;

Reference (14) is described in paragraphs [0002] and [0006] of the present specification;

Reference (15) is described in paragraph [0005] of the present specification;

Reference (16) is described in paragraph [0007] of the present specification;

Reference (17) is described in paragraph [0007] of the present specification;

Reference (18) is described in paragraph [0007] of the present specification;

Reference (19) is described in paragraph [0007] of the present specification;

Reference (20) corresponds to International Publication No. WO 97/23445, which is described in paragraph [0010] of the present specification;

Reference (21) corresponds to International Publication No. WO 00/51954, which is described in paragraph [0010] of the present specification;

Reference (22) is described in paragraph [0011] of the present specification; and

Reference (23) is described in paragraph [0011] of the present specification.

References (22) to (24) are cited in the International Search Report. An English translation of the International Search Report is attached hereto.

References (5) to (9), (12), (16) to (19) and (22) to (24) are Japanese language documents, and English abstracts thereof (except for Reference (6)) are attached thereto.

/Rei Tsang Shiao/ (02/17/2009)